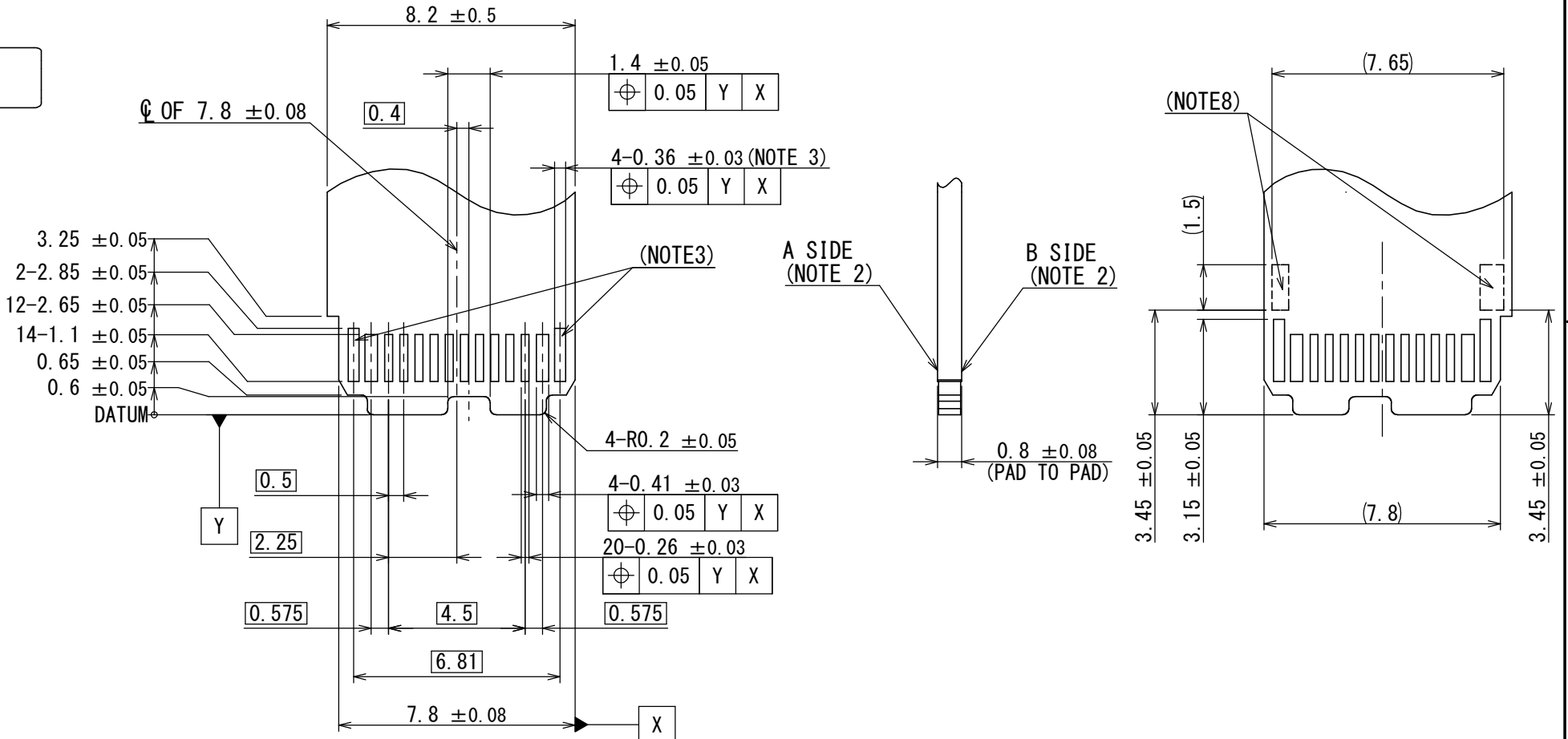
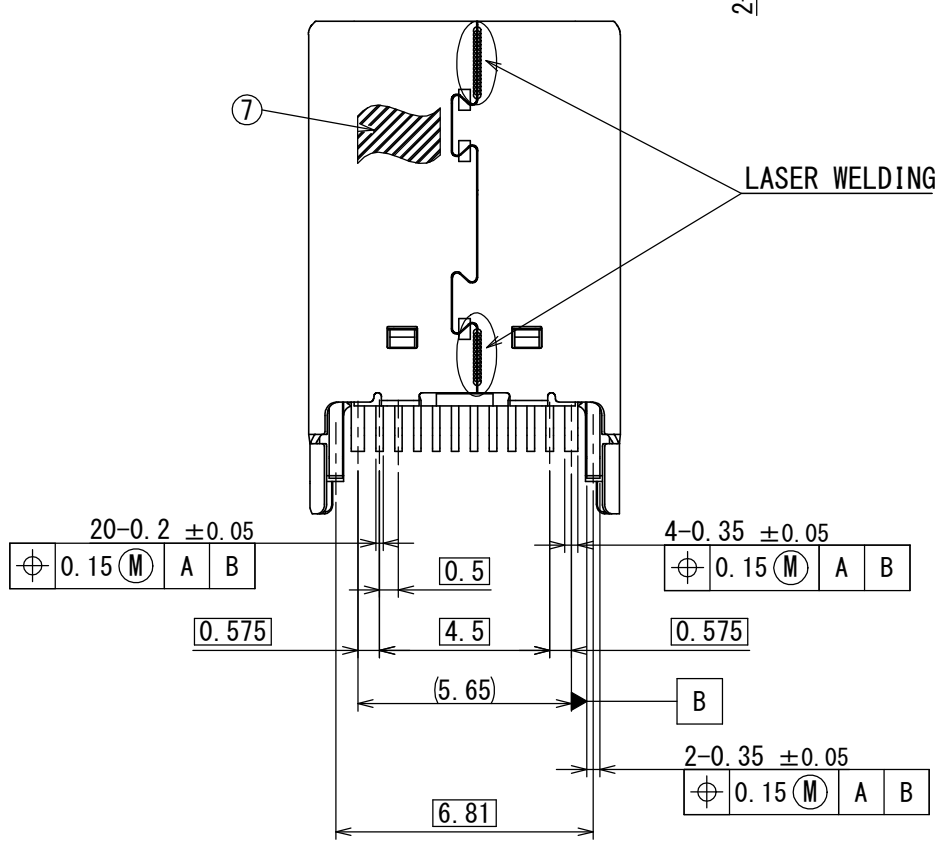
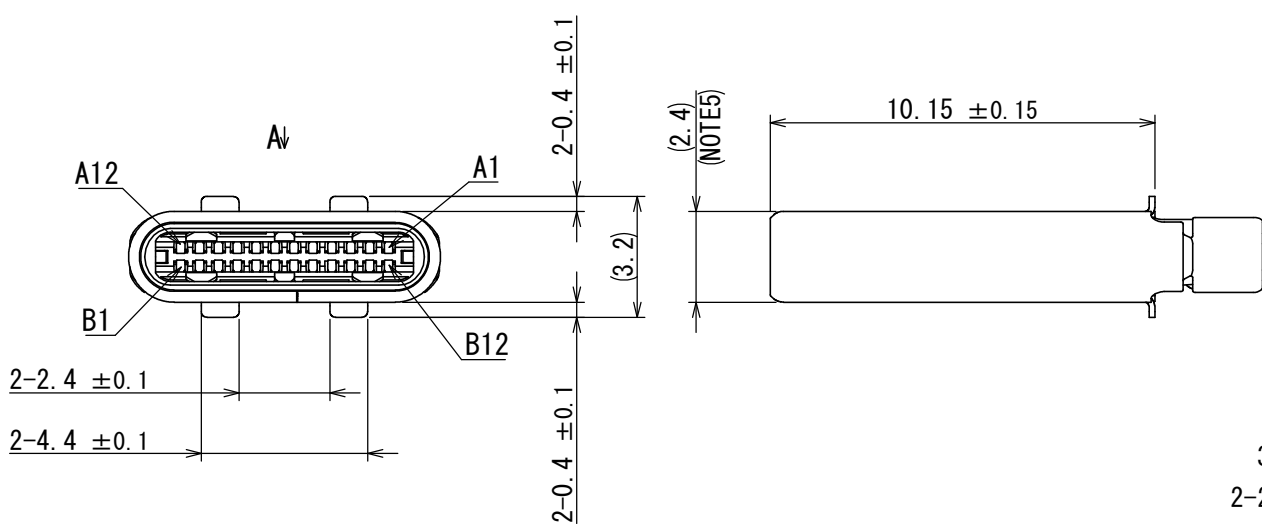
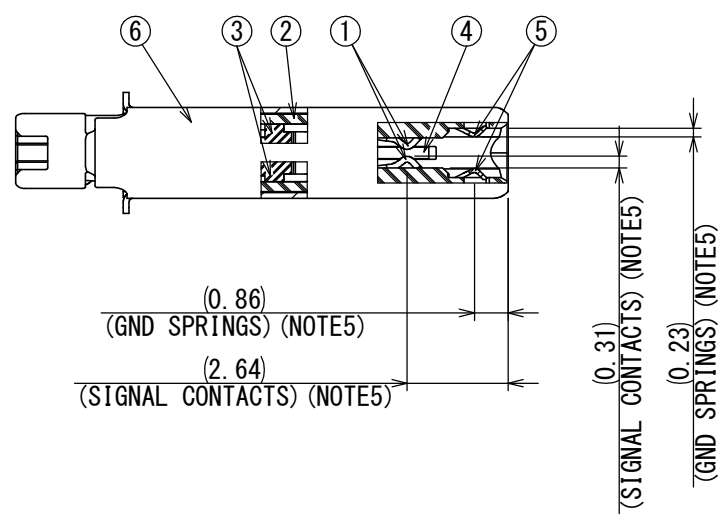
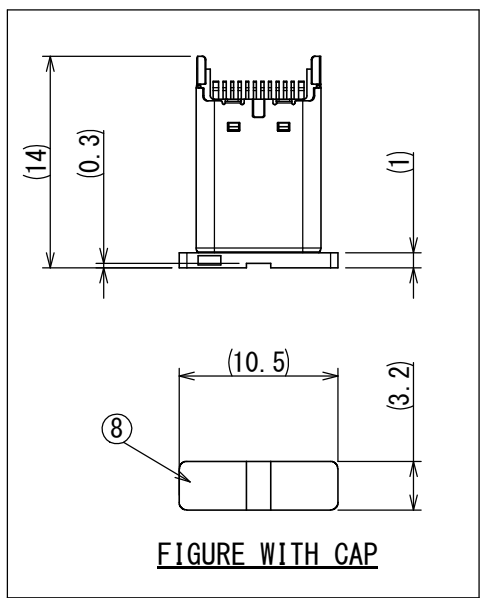
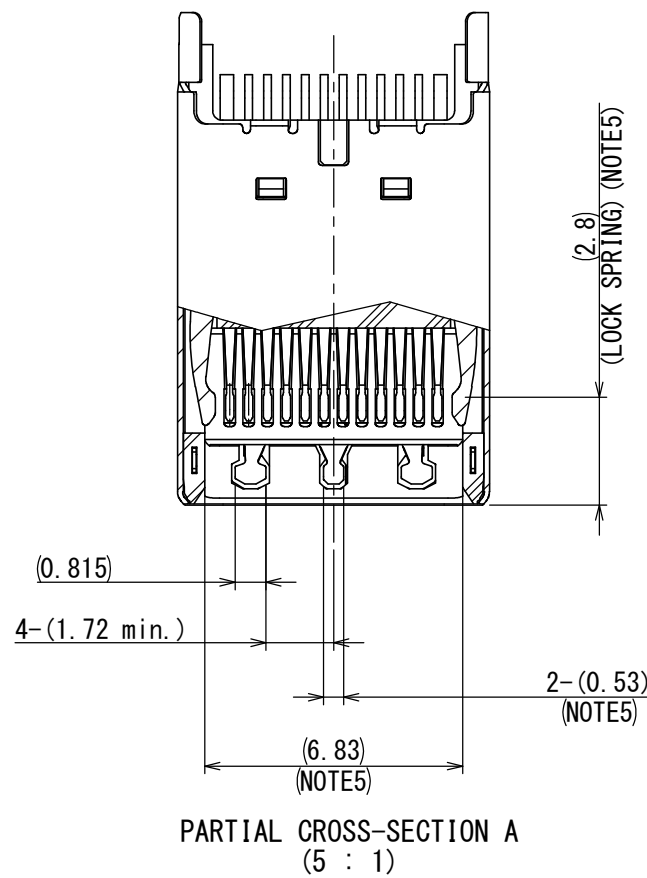
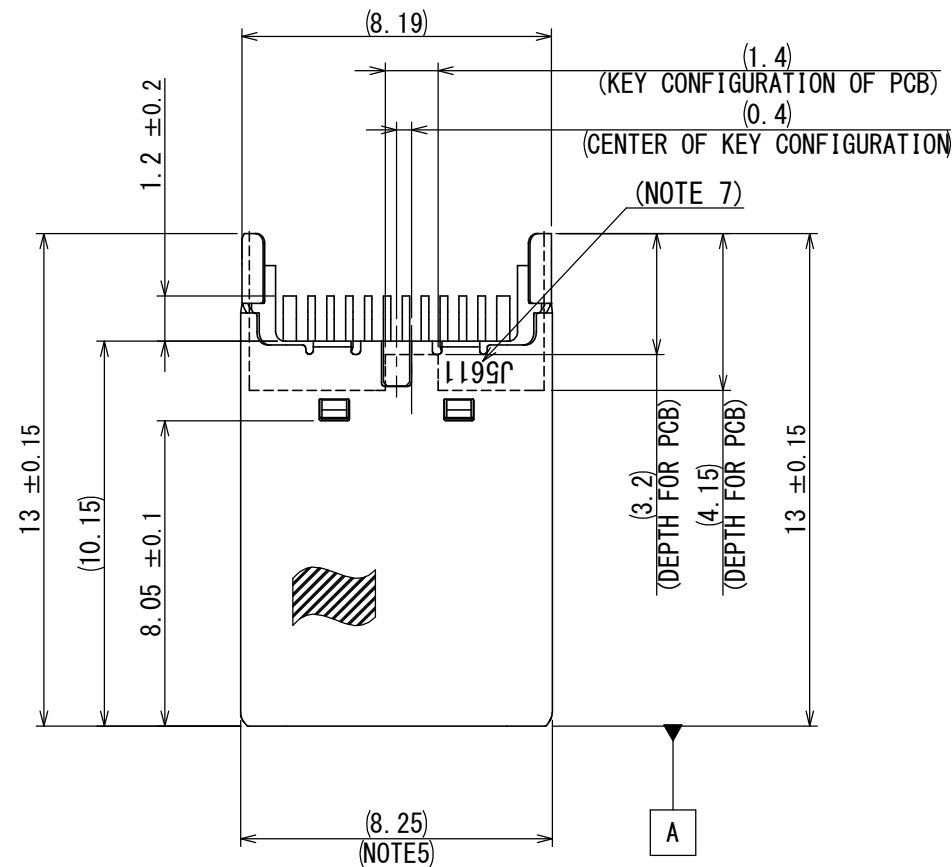




APPLICABLE P. C. B. DIMENSION (REF.)

NOTE1. THERE COULD BE UNRECOGNIZABLE DIFFERENCES FROM ACTUAL PRODUCT DUE TO PROCESS CONVENIENCE BUT NOT IMPACT ON THE FUNCTION.
NOTE2. PCB PADS CONFIGURATION BE SAME BETWEEN A SIDE AND B SIDE.
NOTE3. THERE PADS ARE USED FOR HOLDING PCB.
A SIDE PAD : SHALL NOT BE ELECTRICAL USE AND NOT BE SOLDERED.
B SIDE PAD : ELECTRICAL USE FOR GROUND. NECESSARY TO BE SOLDERED.
NOTE4. RECOMMEND TO KEEP THE CAP STAY IN PLACE UNTIL ALL THE PROCESSES DONE.
THE CAP PREVENTS A CONNECTOR FROM DEFORMED AND CONTAMINATION DURING PROCESSES SUCH AS PADDLE CARD ASSEMBLY AND CABLE ASSEMBLY.
NOTE5. MATING DIMENSIONS CONSIST OF
"Universal Serial Bus Type-C Cable and Connector Specification"
NOTE6. PIN ASSIGNMENT (REF.)

NOTE7. LOT NUMBER IS MARKED AS INDICATED.
【AUTOMATIC MACHINE ASSEMBLY】 : WITH LOT NUMBER
【MANUAL JIG ASSEMBLY】 : WITHOUT LOT NUMBER

(EX) J 5 6 1 1
VENDER ID
YEAR (END OF ONE DIGIT AT A. D.)
MONTH (JAN. TO SEP. : 1 TO 9, OCT. : 0, NOV. : X, DEC. : Y)
DAY (NUMBER OR ALPHABET)
EQUIPMENT No. (NUMBER OR ALPHABET)

NOTE8. RECOMMEND TO UTILIZE THE SIDE SHELL TABS BY SOLDERING TO PCB PADS FOR THE MECHANICAL STRENGTH AND GND CONNECTION.

Pin No.	A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1
	GND	RX2+	RX2-	Vbus	SBU1	D-	D+	CC	Vbus	TX1-	TX1+	GND
Pin No.	B1	B2	B3	B4	B5	B6	B7	B8	B9	B10	B11	B12
	GND	TX2+	TX2-	Vbus	Vconn			SBU2	Vbus	RX1-	RX1+	GND

8	CAP	1	HEAT RESISTING PLASTIC	(BLACK)	HALOGEN-FREE
7	TAPE	2	POLYIMIDE	-	HALOGEN-FREE
6	SHELL	1	STAINLESS STEEL	NICKEL PLATING	NICKEL: 1 μm MIN.
5	GROUND SPRING	2	STAINLESS STEEL	NICKEL PLATING	NICKEL: 0.8 μm MIN.
4	LOCK SPRING	1	STAINLESS STEEL	NICKEL PLATING	NICKEL: 0.8 μm MIN.
3	INSULATOR B	2	HEAT RESISTING PLASTIC	(BLACK)	HALOGEN-FREE
2	INSULATOR A	1	HEAT RESISTING PLASTIC	(BLACK)	HALOGEN-FREE
1	CONTACT	24	COPPER ALLOY	CONTACT AREA: GOLD FLASH OVER PALLADIUM-NICKEL OVER NICKEL SOLDER TAILS: GOLD FLASH OVER NICKEL	CONTACT AREA: NICKEL: 2 μm MIN. PALLADIUM-NICKEL: 0.75 μm MIN. GOLD FLASH: 0.05 μm MIN. SOLDER TAILS: NICKEL: 2 μm MIN. GOLD FLASH: 0.03 μm MIN.

符号 NO.	名 DESCRIPTION	個 QTY.	材 MATERIAL	仕 FINISH	備 REMARKS
仕様書 (SPECIFICATION) JACS-30353 JAH-30353			第1版 (ORIGINAL DATE) 18/DEC/2015		尺度 (SCALE) 5:1
一般公差 (GENERAL TOLERANCE)			製図 DR.		シリーズ (SERIES) DX07
寸法 (DIMENSION).			担当 CHK.		名称 (TITLE) DX07P024AJ1
角度 (ANGLES)			査閲 APPD.		
承認 APPD.			承認 APPD.		
単位 (UNIT) : mm			質量 (MASS)		

日本航空電子工業株式会社
JAE
JAPAN AVIATION
ELECTRONICS
INDUSTRY, LTD.

図面番号 (DRAWING NO.)
SJ116680

版数
(VER.)
1